

MC11606C6WR-BNMLW 1 x 16		6mm Character Height	LCD Module				
Specification							
Version: 2		Date: 25/02/2016					
	Revision						
1 2	First issue Modify Precautions in use of LCD Modules &	Static electricity test					

Display F	eatures		
Character Count	1 x 16		
Appearance	White on Blue		
Logic Voltage	5V		
Interface	Parallel		
Font Set	Cyrillic		Compliant
Display Mode	Transmissive		ampliant
Character Height	6.56mm		ompliant
LC Type	STN Blue		
Module Size	85.00 x 28.00 x 13.50mm		
Operating Temperature	-20°C ~ +70°C		
Construction	СОВ	Box Quantity	Weight / Display
LED Backlight	White		

* - For full design functionality, please use this specification in conjunction with the ST7066U specification. (Provided Separately)

Display Accessories						
Part Number	Description					

Optional Variants								
s Voltage								
•								

General Specification

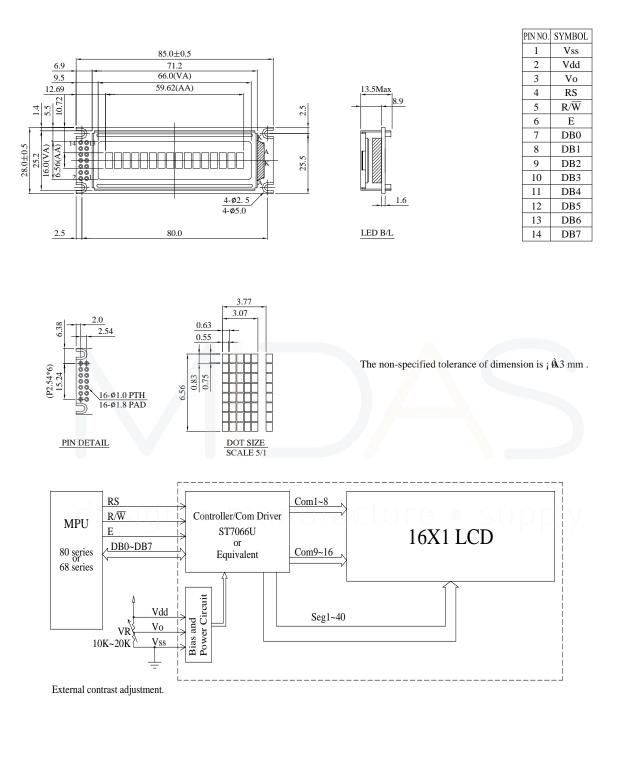
The Features is described as follow:

- Module dimension: 85.0 x 28.0 x 13.5 (max.) mm
- View area: 66.0 x 16.0 mm
- Active area: 59.62 x 6.56 mm
- Number of Characters: 16 characters x 1Lines
- Dot size: 0.55 x 0.75 mm
- Dot pitch: 0.63 x 0.83 mm
- Character size: 3.07 x 6.56 mm
- Character pitch: 3.77 x 6.56 mm
- LCD type: STN Negative, Blue Transmissive
- Duty: 1/16
- View direction: 6 o'clock
- Backlight Type: LED, White
- IC: ST7066U

Interface Pin Function

Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	Vdd	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H:DATA, L:Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line

Contour Drawing & Block Diagram



 Character located
 1
 2
 3
 4
 5
 6
 7
 8
 9
 10
 11
 12
 13
 14
 15
 16

 DDRAM address
 00
 01
 02
 03
 04
 05
 06
 07
 40
 41
 42
 43
 44
 45
 46
 47

2-line display mode.

Character Generator ROM Pattern

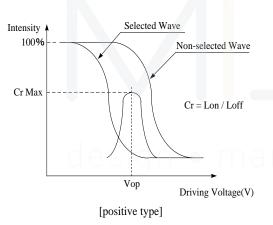
Table.2

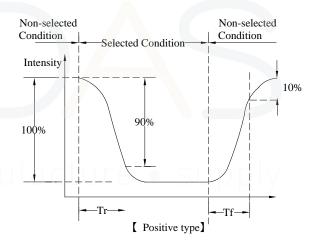
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)														Д	5.6
0001	(2)					0	3	-				9	ш		Ц	5
0010	(3)		11	2	B	R	b					8			Щ	52
0011	(4)		#								H	8			æ	1.
0100	(5)		\$	4	D	1	c	ŧ.								
0101	(6)		2		E	U	œ				И	ë				
0110	(7)		8.	6		Ų	1°				04	188	10		Щ	14.
0111	(8)			1		W	-				.11		93			Ŀ
1000	(1)					X		24								
1001	(2)				1	v						0ă		*		
1010	(3)		*	*							٩	ĸ				4
1011	(4)				ĸ	I.		10			-					4
1100	(5)					\$		12								2
1101	(6)		••••		M	1	m	15			1.	Н				8
1110	(7)											m				
1111	(8)				0		0	æ								

Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	ψ= 180°
	θ	CR≧2	0	_	40	ψ= 0°
View Angle	θ	CR≧2	0	—	30	ψ= 90°
	θ	CR≧2	0	_	30	ψ= 270°
Contrast Ratio	CR	_		3		_
	T rise	_		150	200	ms
Response Time	T fall	_	- 150 200 i	ms		

Definition of Operation Voltage (Vop)





Definition of Response Time (Tr, Tf)

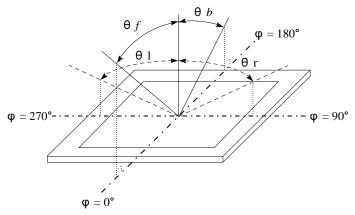
Conditions :

Operating Voltage : Vop

Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≧2)



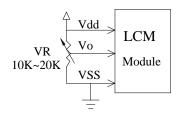
Absolute Maximum Ratings

ltem	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30		+80	°C
Input Voltage	Vı	Vss		V _{DD}	V
Supply Voltage For Logic	Vdd-Vss	-0.3	_	7	V
Supply Voltage For LCD	V _{DD} -V _o	-0.3		13	V

Electrical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For						
Logic	VDD-Vss	-	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20°C	_	_	5.5	V
*Note	VDD-V0	Ta=25°C	4.2	4.35	4.5	V
		Ta=70°C	3.5	—	_	V
Input High Volt.	Vін	_	0.7 V _{DD}	_	V _{DD}	V
Input Low Volt.	Vil	_	Vss	_	0.6	V
Output High Volt.	Vон	_	3.9	_	Vdd	V
Output Low Volt.	Vol		0	_	0.4	V
Supply Current	ldd	V _{DD} =5.0V	1.0	1.2	1.5	mA

* Note: Please design the VOP adjustment circuit on customer's main board



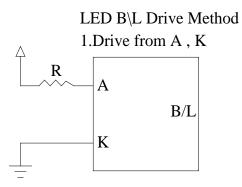
Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	32	40	mA	V=3.5V
Supply Voltage	v	3.4	3.5	3.6	v	_
Reverse Voltage	VR	_	_	5	v	_
Luminance (Without LCD)	IV	496	620	_	CD/M ²	ILED=32mA
LED Life Time (For Reference only)	_		50K	_	Hr.	ILED=32mA 25°C,50-60%RH, (Note 1)
Color	White				-	

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



Reliability

Content of Reliability Test (Wide temperate	ure, -20℃~70°C)
---------------------------------------------	-----------------

	Environmental Test							
Test Item	Content of Test	Test Condition	Note					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs						
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles						
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

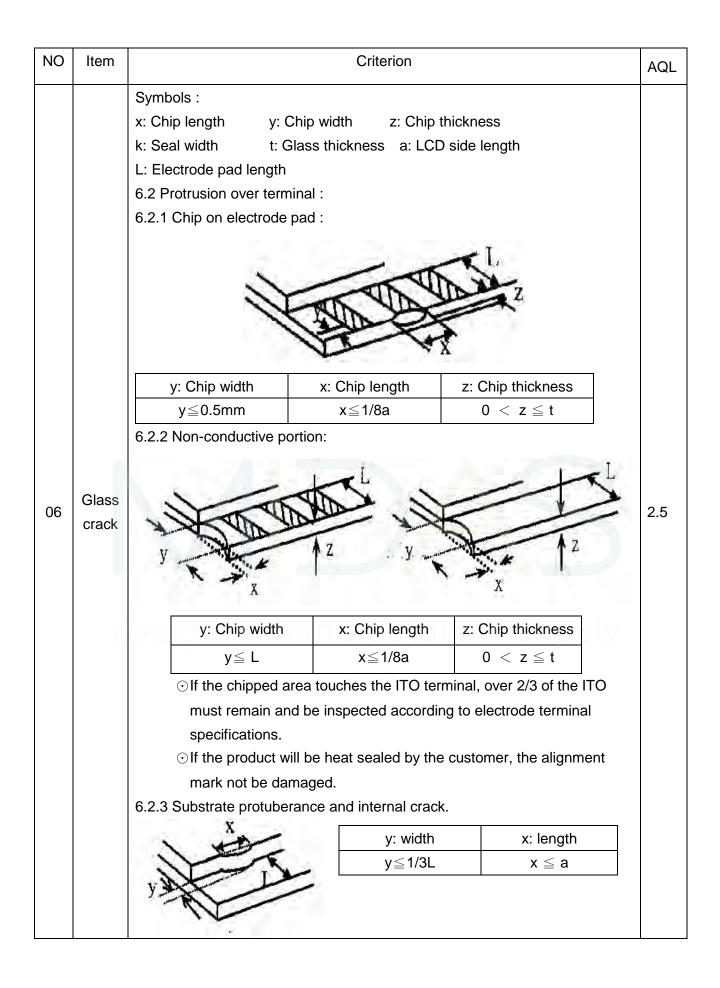
Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing Black or white	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 2.1 White and black spots on display ≤ 0.25mm, no more than 				
02	spots on LCD (display only)	three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm				
03	LCD black spots, white spots, contamination (non-display)	 3.1 Round type : Φ=(x + y)/2 3.2 Line type : (A 	2 2 4 7 7	SIZE $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.20$ $0.20 < \Phi \leq 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vis judge using blac specifications, no to find, must che specify direction	k spot ot easy eck in	Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5

NO	Item	Criterion			
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
05	Scratches	Symbols Define: x: Chip length y: k: Seal width t: C L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sur $\begin{array}{c} \hline \hline$	Symbols Define: x: Chip length y: Chip width z: Chip thickness x: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: Image: Chip thickness y: Chip width x: Chip length z: Chip thickness y: Chip width x: Chip length Z = 1/2t Not over viewing x = 1/8a 1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a Olf there are 2 or more chips, x is total length of each chip. x = 1/8a		2.5
		$ z: Chip thickness Z \leq 1/2t $	y: Chip width Not over viewing area	x: Chip length x≦1/8a	
		1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
		\odot If there are 2 or more	e chips, x is the total leng	th of each chip.	



NO	Item	Criterion	AQL	
07	Cracked glass	The LCD with extensive crack is not acceptable.		
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 		
09	Bezel	 8.3 Backlight doesn't light or color wrong. 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications. 	0.65 2.5 0.65	
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than 	2.5 2.5 0.65 2.5	
10	PCB · COB	 three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	 2.5 0.65 0.65 2.5 2.5 	
11	Soldering	 X * Y<=2mm2 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65	

NO	Item	Criterion	AQL	
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.12.2 No cracks on interface pin (OLB) of TCP.		
		12.3 No contamination, solder residue or solder balls on product.	2.5	
		12.4 The IC on the TCP may not be damaged, circuits.	2.5	
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to	2.5	
		sever.		
12	General	12.6 The residual rosin or tin oil of soldering (component or chip		
	appearance	component) is not burned into brown or black color.	2.5	
		12.7 Sealant on top of the ITO circuit has not hardened.		
		12.8 Pin type must match type in specification sheet.	0.65	
		12.9 LCD pin loose or missing pins.	0.65	
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65	
		12.11 Product dimension and structure must conform to product specification sheet.		
		12.12 Visual defect outside of VA is not considered to be rejection.		

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Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) MIDAS have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) MIDAS have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, MIDAS have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

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Material List of Components for RoHs

1. MIDAS hereby declares that all of or part of products (with the mark

"#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2. Process for RoHS requirement : (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C ;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.